



Call for Papers LOPEC 2018



Exhibition: March 14–15, 2018 Conference: March 13–15, 2018

Messe München, Germany

Important dates

- Deadline for submission of abstracts: October 12, 2017
- Notification of acceptance: December 7, 2017
- Presentation dates: March 13-15, 2018

We invite you to actively participate in LOPEC 2018 and look forward to receiving your submission at callforpapers.lopec.com

General Chair:

Wolfgang Mildner, MSW (DE), Founder and CEO

Business Conference Chair:

John LeMoncheck, Cambrios (US), CEO

Technical Conference Chair:

Dr. Ton van Mol, Holst Centre (NL), Managing Director

Scientific Conference Chair:

Prof. Antonio Facchetti,

Northwestern University / Flexterra (US)

Present your latest research results, business models or innovative developments in the perfect setting—and make a valuable contribution to LOPEC 2018. All confirmed speakers from industry and research qualify for the discounted academic ticket rate. Whether you give a lecture or present a poster, three different conference components are available for your presentation:

Business Conference topics

- End-user applications and requirements
- Business and product developments
- Supply-chain challenges
- Market and industry forecasts
- IP and licensing strategies to monetize technology

Start-up Forum: Present your business concepts, applications and technologies in the context of printed electronics to the entire industry and possible investors. Take advantage of this chance to introduce your company to a broad-based audience at the leading event for printed electronics.

Technical Conference topics

- 3D MID (mechatronic interconnect devices)
- Biomedical applications
- Energy
- Flexible displays and lighting
- Functional materials
- IoT (Internet of Things)
- Lighting in mobility applications
- Publicly funded projects

- Substrates and Encapsulation
- Smart and hybrid systems
- Touch, tactile and haptic feedback
- Upscaling production and manufacturing processes
- Wearable electronics

Scientific Conference topics

- Materials
- Devices
- Processes
- Thin-film analysis and characteriztion
- Circuit design, simulations and systems

lopec.com/callforpapers

International Exhibition and Conference for the Printed Electronics Industry

